



Product / Package Information	
Package:	EWLP
Body Size (mm):	
I/O Count:	6
Terminal Finish	Copper

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

### Materials Declaration

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.71 E-04	100.00	1000000	91.43	914287

#### External Plating Finish

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.12 E-05	100.00	1000000	2.17	21741

#### UBM / Redistribution Layers

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.90 E-05	93.82	938226	3.68	36809
Other inorganic materials	Tungsten	7440-33-7	1.12E-06	5.56	55587	0.22	2181
Other inorganic materials	Titanium	7440-32-6	1.25E-07	0.62	6187	0.02	243
Subtotal			2.02 E-05	100.00	1000000	3.92	39233

#### Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Photosensitive PolyimideResin	Proprietary		30-60			
Other organic materials	Acrylate Ester	Proprietary		5-10			
Others	Proprietary Ingredients	Proprietary		1-5			
Subtotal			1.28E-05	100	1000000	2.47	24739

Package Totals	Weight (g)	Percentage (%)	PPM
	5.16 E-04	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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